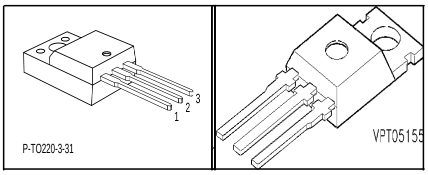
Cool MOS™ Power Transistor

V_{DS}	800	V
$R_{DS(on)}$	0.65	Ω
I_D	8	A

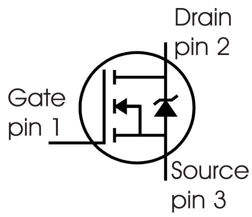
Feature

- New revolutionary high voltage technology
- Ultra low gate charge
- Periodic avalanche rated
- Extreme d*v*/d*t* rated
- Ultra low effective capacitances
- Improved transconductance
- P-TO-220-3-31: Fully isolated package (2500 VAC; 1 minute)

P-TO220-3-31 P-TO220-3-1



Type	Package	Ordering Code	Marking
SPP08N80C3	P-TO220-3-1	Q67040_S4436	08N80C3
SPA08N80C3	P-TO220-3-31	Q67040-S4437	08N80C3



Maximum Ratings

Parameter	Symbol	Value		Unit
		SPP	SPA	
Continuous drain current	I_D			A
T_C = 25 °C		8	8[1)]	
T_C = 100 °C		5.1	5.1[1)]	
Pulsed drain current, t_p limited by T_{jmax}	$I_{D\ puls}$	24	24	A
Avalanche energy, single pulse I_D=1.6A, V_{DD}=50V	E_{AS}	340	340	mJ
Avalanche energy, repetitive t_{AR} limited by T_{jmax}[2)] I_D=8A, V_{DD}=50V	E_{AR}	0.2	0.2	
Avalanche current, repetitive t_{AR} limited by T_{jmax}	I_{AR}	8	8	A
Gate source voltage	V_{GS}	±20	±20	V
Gate source voltage AC (f >1Hz)	V_{GS}	±30	±30	
Power dissipation, T_C = 25°C	P_{tot}	104	40	W
Operating and storage temperature	T_j , T_{stg}	-55...+150		°C

Maximum Ratings

Parameter	Symbol	Value	Unit
Drain Source voltage slope V_{DS} = 640 V, I_D = 8 A, T_j = 125 °C	dv/dt	50	V/ns

Thermal Characteristics

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Thermal resistance, junction - case	R_{thJC}	-	-	1.2	K/W
Thermal resistance, junction - case, FullPAK	R_{thJC_FP}	-	-	3.8	
Thermal resistance, junction - ambient, leaded	R_{thJA}	-	-	62	
Thermal resistance, junction - ambient, FullPAK	R_{thJA_FP}	-	-	80	
Soldering temperature, 1.6 mm (0.063 in.) from case for 10s [3]	T_{sold}	-	-	260	°C

Electrical Characteristics, at T_j=25°C unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Drain-source breakdown voltage	$V_{(BR)DSS}$	V_{GS}=0V, I_D=0.25mA	800	-	-	V
Drain-Source avalanche breakdown voltage	$V_{(BR)DS}$	V_{GS}=0V, I_D=8A	-	870	-	
Gate threshold voltage	$V_{GS(th)}$	I_D=470µA, V_{GS}=V_{DS}	2.1	3	3.9	
Zero gate voltage drain current	I_{DSS}	V_{DS}=800V, V_{GS}=0V, T_j=25°C T_j=150°C	 - -	 0.5 -	 20 200	µA
Gate-source leakage current	I_{GSS}	V_{GS}=20V, V_{DS}=0V	-	-	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	V_{GS}=10V, I_D=5.1A T_j=25°C T_j=150°C	 - -	 0.56 1.5	 0.65 -	Ω
Gate input resistance	R_G	f=1MHz, open drain	-	0.7	-	

Electrical Characteristics

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Transconductance	g_{fs}	$V_{DS}\geq 2*I_D*R_{DS(on)max}$, I_D=5.1A	-	5.5	-	S
Input capacitance	C_{iss}	V_{GS}=0V, V_{DS}=25V, f=1MHz	-	1100	-	pF
Output capacitance	C_{oss}		-	500	-	
Reverse transfer capacitance	C_{rss}		-	25	-	
Effective output capacitance,[4)] energy related	$C_{o(er)}$	V_{GS}=0V, V_{DS}=0V to 480V	-	31.8	-	
Effective output capacitance,[5)] time related	$C_{o(tr)}$		-	70	-	
Turn-on delay time	$t_{d(on)}$	V_{DD}=400V, V_{GS}=0/10V, I_D=8A, R_G=10Ω	-	25	-	ns
Rise time	t_r		-	15	-	
Turn-off delay time	$t_{d(off)}$		-	65	75	
Fall time	t_f		-	7	10	

Gate Charge Characteristics

Parameter	Symbol	Conditions	min.	typ.	max.	Unit
Gate to source charge	Q_{gs}	V_{DD}=640V, I_D=8A	-	4.6	-	nC
Gate to drain charge	Q_{gd}		-	21	-	
Gate charge total	Q_g	V_{DD}=640V, I_D=8A, V_{GS}=0 to 10V	-	40	52	
Gate plateau voltage	$V_{(plateau)}$	V_{DD}=640V, I_D=8A	-	6	-	V

[1]Limited only by maximum temperature

[2]Repetitve avalanche causes additional power losses that can be calculated as $P_{AV}=E_{AR}*f$.

[3]Soldering temperature for TO-263: 220°C, reflow

[4]$C_{o(er)}$ is a fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS}.

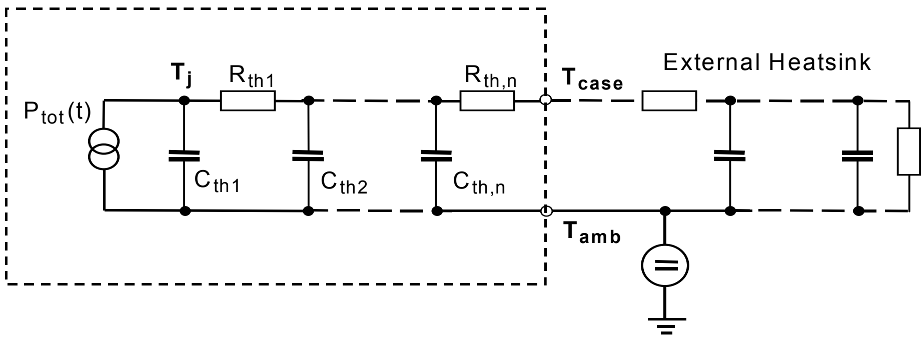
[5]$C_{o(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS}.

Electrical Characteristics

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Inverse diode continuous forward current	I_S	T_C=25°C	-	-	8	A
Inverse diode direct current, pulsed	I_{SM}		-	-	24	
Inverse diode forward voltage	V_{SD}	V_{GS}=0V, I_F=I_S	-	1	1.2	V
Reverse recovery time	t_{rr}	V_R=640V, I_F=I_S ,	-	550	-	ns
Reverse recovery charge	Q_{rr}	di_F/dt=100A/µs	-	7	-	µC
Peak reverse recovery current	I_{rrm}		-	24	-	A
Peak rate of fall of reverse recovery current	di_{rr}/dt	T_j=25°C	-	500	-	A/µs

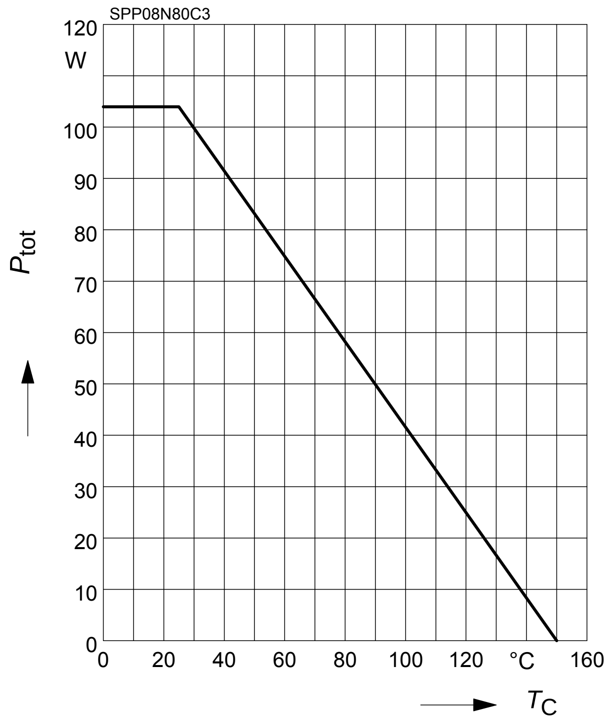
Typical Transient Thermal Characteristics

Symbol	Value		Unit	Symbol	Value		Unit
	SPP	SPA			SPP	SPA	
R_{th1}	0.017	0.017	K/W	C_{th1}	0.0001741	0.0001741	Ws/K
R_{th2}	0.032	0.032		C_{th2}	0.0006598	0.0006598	
R_{th3}	0.06	0.06		C_{th3}	0.0009193	0.0009193	
R_{th4}	0.245	0.189		C_{th4}	0.002607	0.002607	
R_{th5}	0.266	0.414		C_{th5}	0.005878	0.007619	
R_{th6}	0.101	2.518		C_{th6}	0.051	0.412	



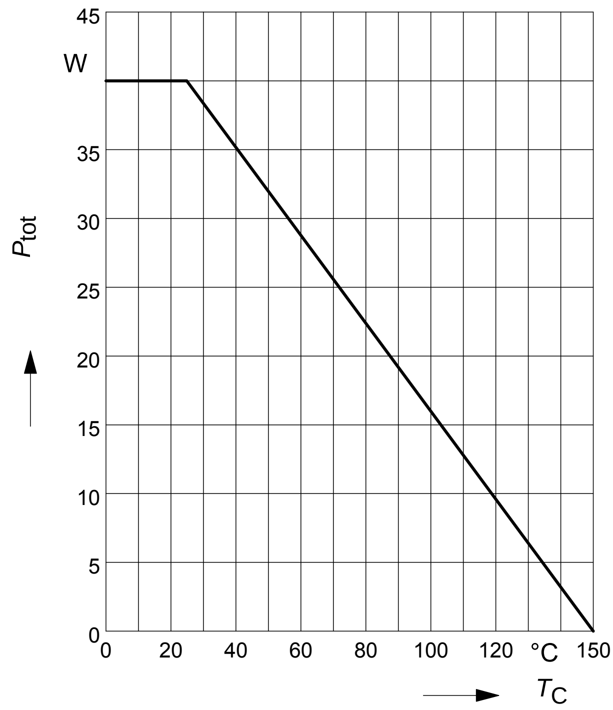
1 Power dissipation

$P_{tot} = f(T_C)$



2 Power dissipation FullPAK

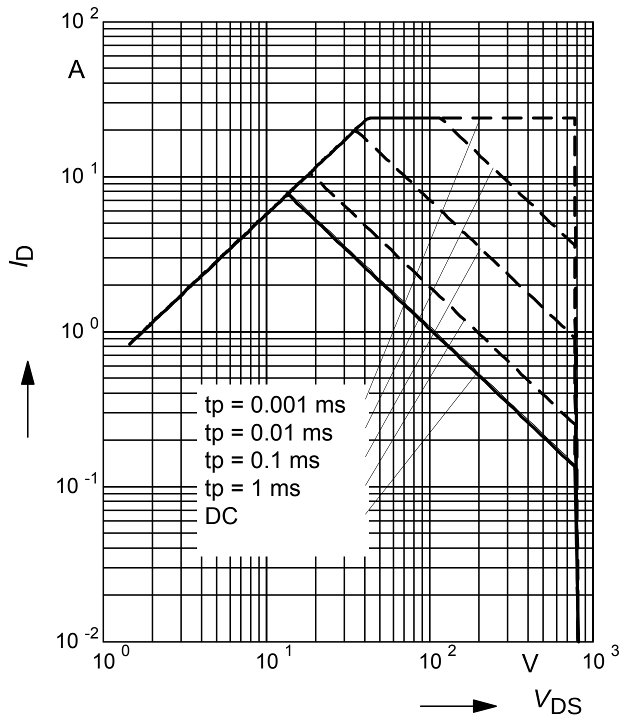
$P_{tot} = f(T_C)$



3 Safe operating area

$I_D = f(V_{DS})$

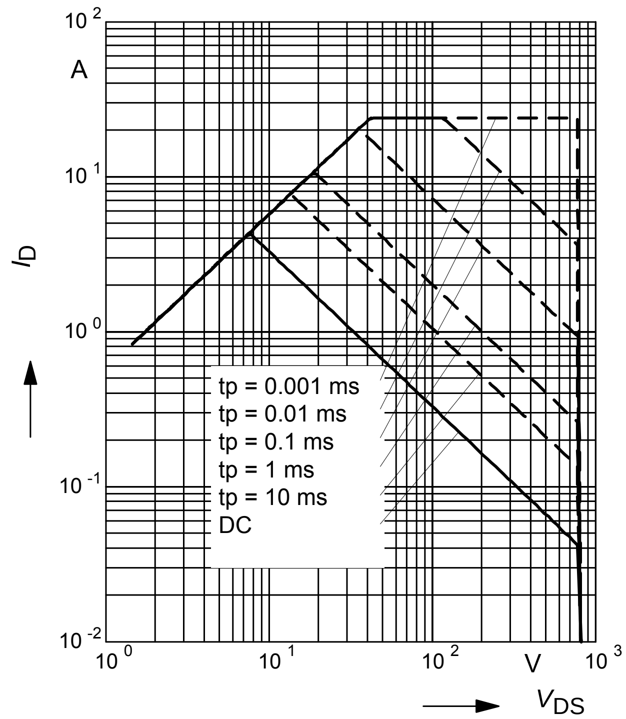
parameter : $D = 0$, T_C=25°C



4 Safe operating area FullPAK

$I_D = f(V_{DS})$

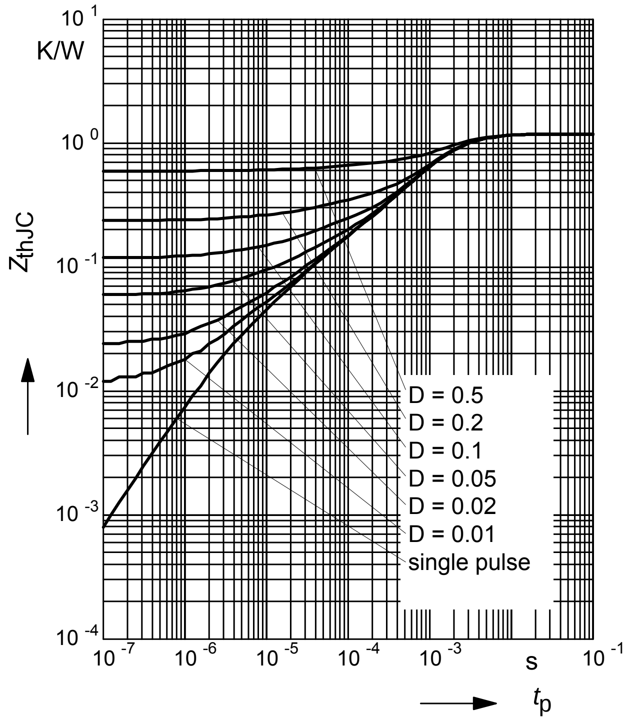
parameter: $D = 0$, T_C = 25°C



5 Transient thermal impedance

$Z_{thJC} = f(t_p)$

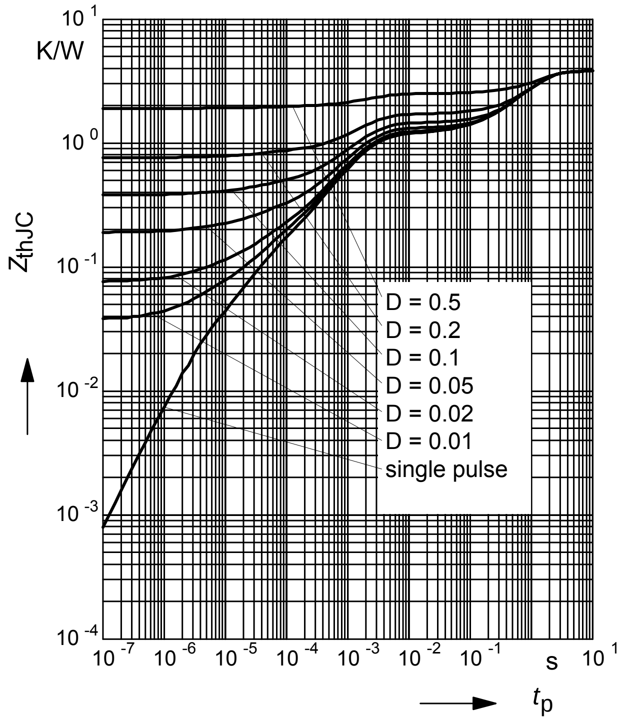
parameter: $D = t_p/T$



6 Transient thermal impedance FullPAK

$Z_{thJC} = f(t_p)$

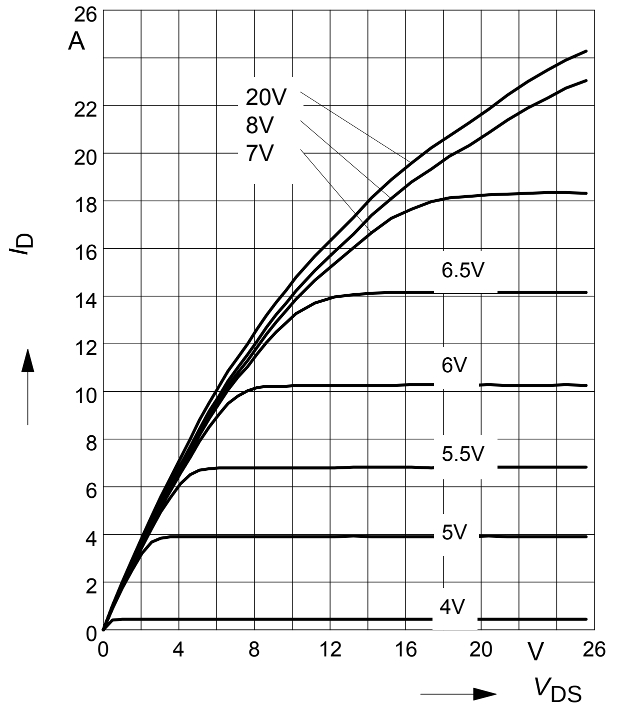
parameter: $D = t_p/t$



7 Typ. output characteristic

$I_D = f(V_{DS})$; T_j=25°C

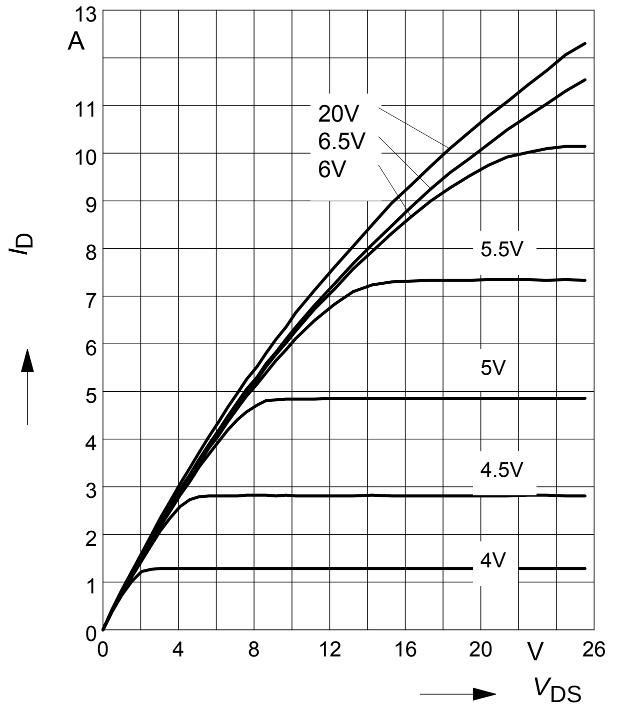
parameter: t_p = 10 µs, V_{GS}



8 Typ. output characteristic

$I_D = f(V_{DS})$; T_j=150°C

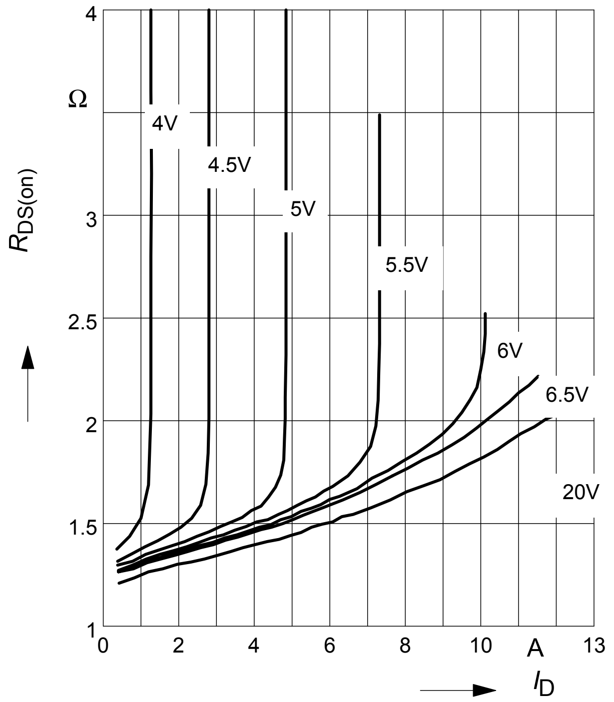
parameter: t_p = 10 µs, V_{GS}



9 Typ. drain-source on resistance

$R_{DS(on)}=f(I_D)$

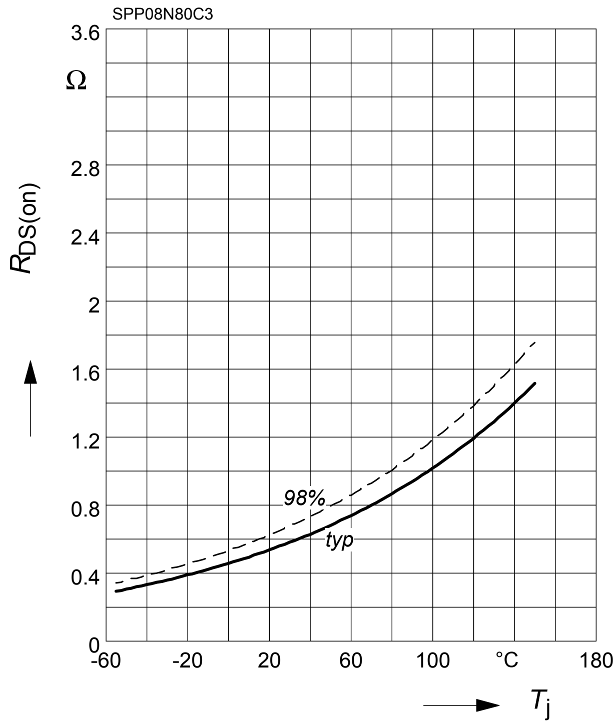
parameter: T_j=150°C, V_{GS}



10 Drain-source on-state resistance

$R_{DS(on)} = f(T_j)$

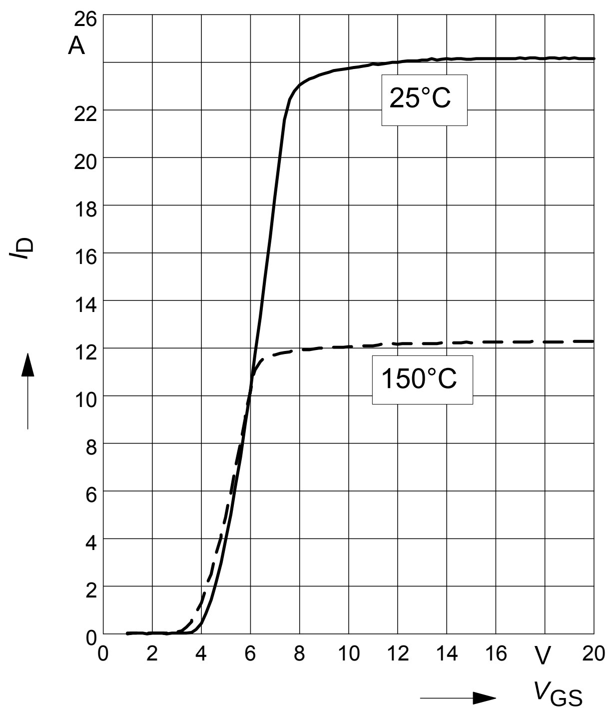
parameter : I_D = 5.1 A, V_{GS} = 10 V



11 Typ. transfer characteristics

$I_D= f(V_{GS})$; $V_{DS}\geq 2 \times I_D \times R_{DS(on)max}$

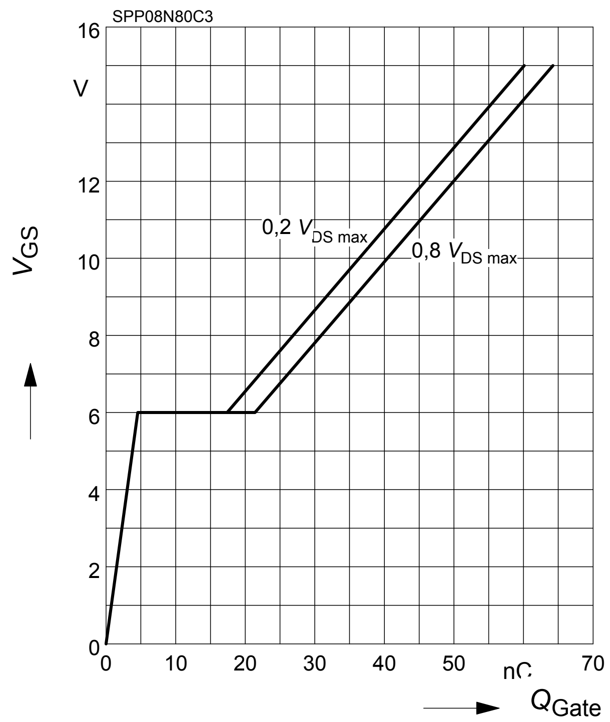
parameter: t_p = 10 µs



12 Typ. gate charge

$V_{GS} = f(Q_{Gate})$

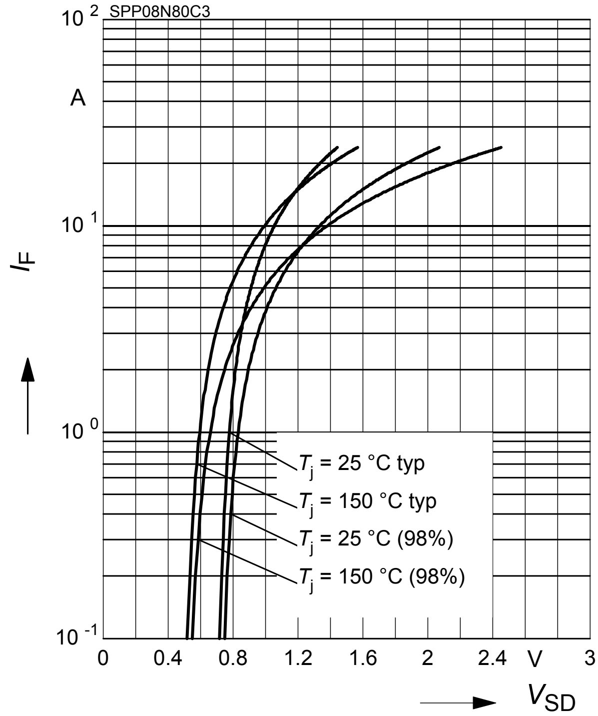
parameter: I_D = 8 A pulsed



13 Forward characteristics of body diode

$I_F = f(V_{SD})$

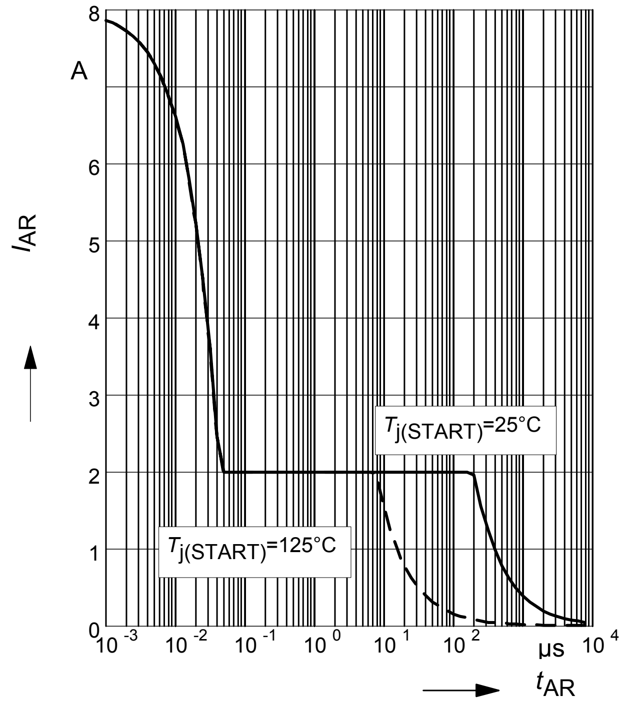
parameter: T_j , tp = 10 µs



14 Avalanche SOA

$I_{AR} = f(t_{AR})$

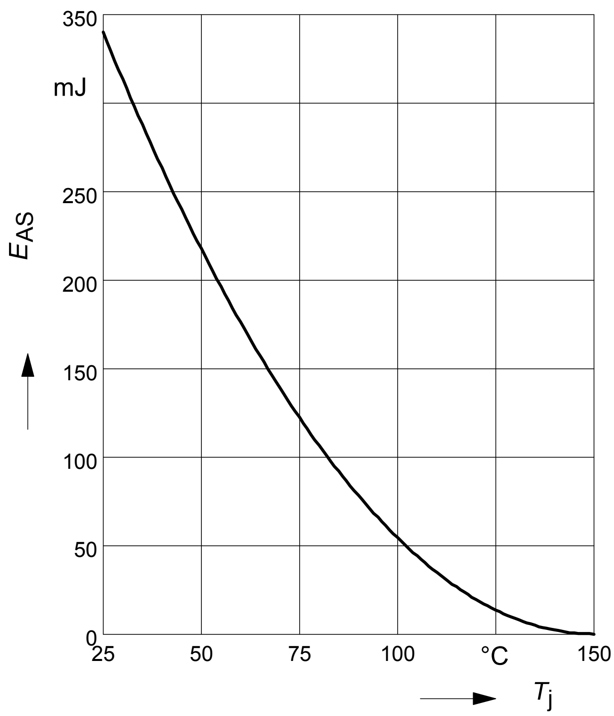
par.: $T_j \leq 150$ °C



15 Avalanche energy

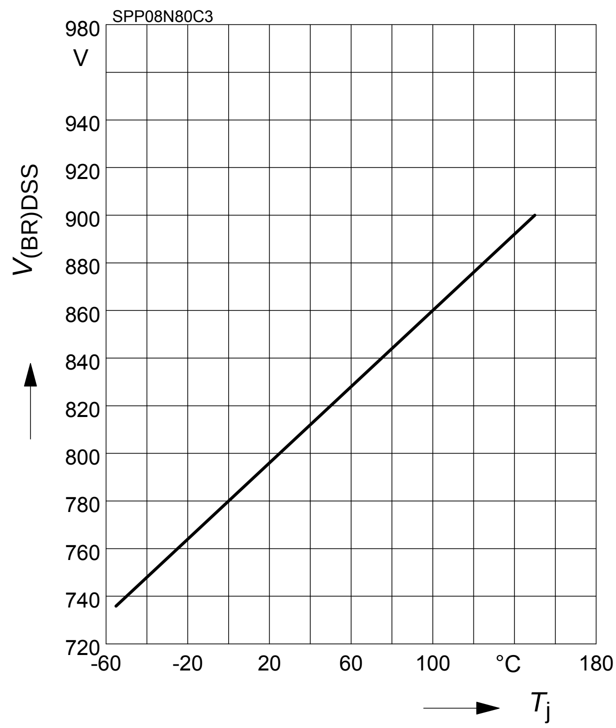
$E_{AS} = f(T_j)$

par.: I_D = 1.6 A, V_{DD} = 50 V



16 Drain-source breakdown voltage

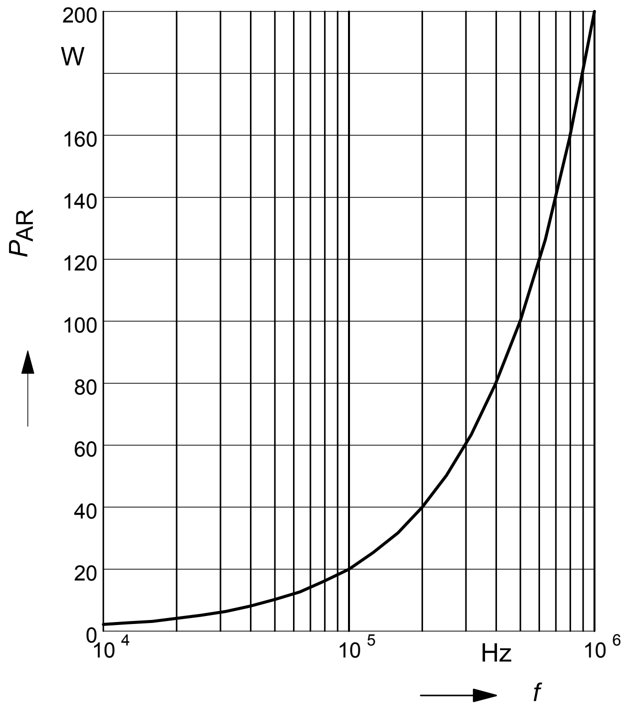
$V_{(BR)DSS} = f(T_j)$



17 Avalanche power losses

$P_{AR} = f(f)$

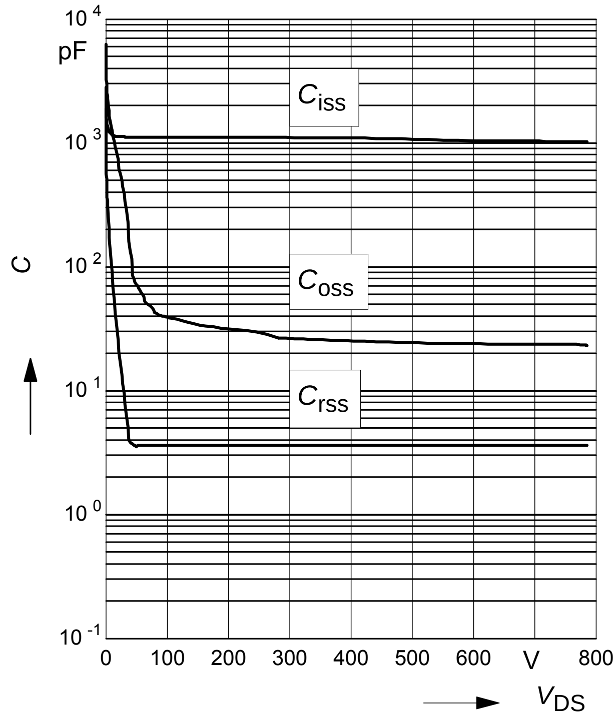
parameter: E_{AR}=0.2mJ



18 Typ. capacitances

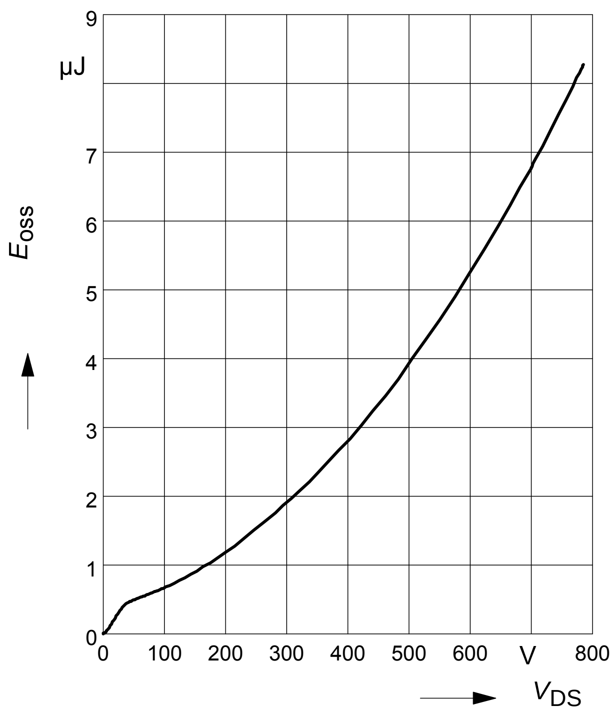
$C = f(V_{DS})$

parameter: V_{GS}=0V, f=1 MHz

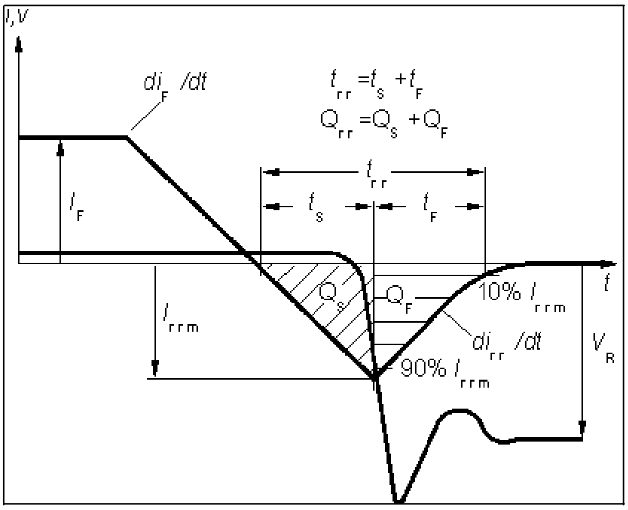


19 Typ. C_{oss} stored energy

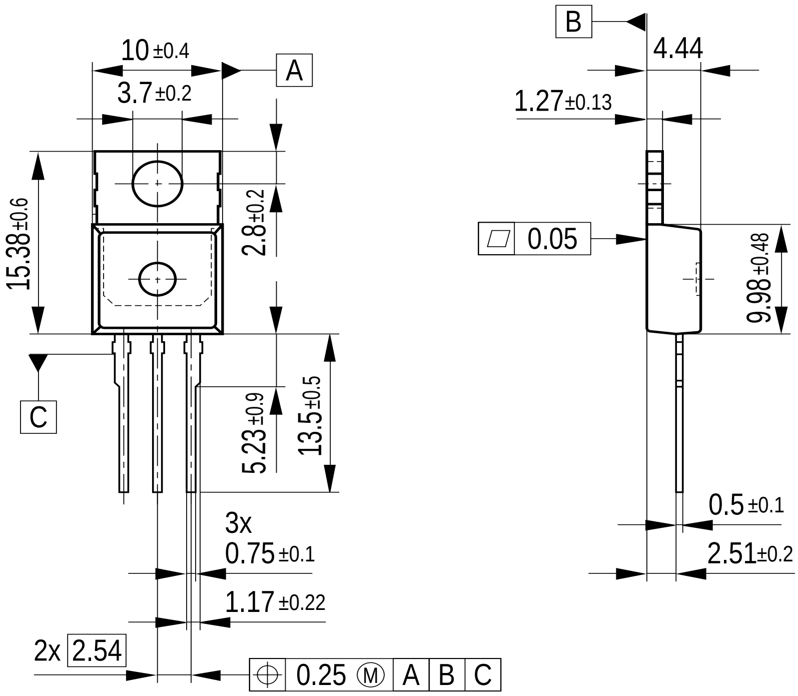
$E_{oss}=f(V_{DS})$



Definition of diodes switching characteristics

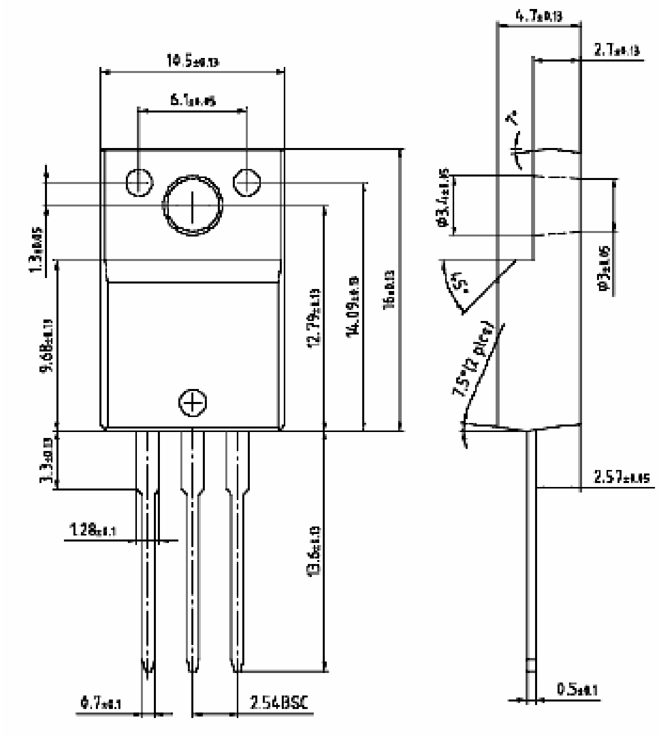


P-TO-220-3-1



All metal surfaces tin plated, except area of cut.
Metal surface min. x=7.25, y=12.3

P-TO-220-3-31 (FullPAK)



Please refer to mounting instructions (application note AN-TO220-3-31-01)

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